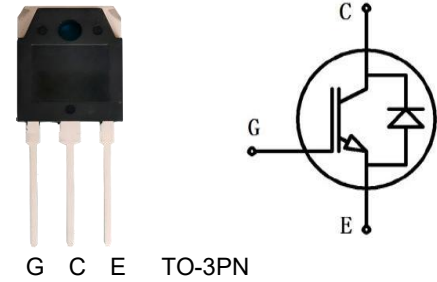


Trench Field-stop IGBT Discretes

VCES	VCEsat		Ic
1350V	Tvj=25°C	2.3V	30A/60A
	Tvj= 150°C	2.8V	



FEATURES

- Trench and Field-stop technology
- Low collector to emitter saturation voltage
- Optimized for Fast Switching
- Easy parallel switching capability
- Short circuit withstands time-10μs

APPLICATIONS

- Induction Heating
- Soft switching application

Absolute Maximum Ratings of IGBT (Tj= 25°C unless otherwise noted)

Symbol	Parameter	Conditions	Value	Unit
VCES	Collector to Emitter Voltage		1350	V
VGES	Continuous Gate to Emitter Voltage		±20	V
Ic	Continuous Collector Current	Tc=100°C	30	A
		Tc=25°C	60	A
IcM	Pulse Collector Current	Pulse width limited by Tjmax	120	A
PD	Maximum Power Dissipation (IGBT)	Tc=25°C, Tj=150°C	347	W
tsc	Short Circuit Withstand Time	Vcc=600V, VGE≤15V	10	μs

Electrical Characteristics of IGBT(T=25°C)

Static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VGE(th)	Gate-Emitter Threshold Voltage	Ic=1mA, VcE=VGE, Tj=25°C	4.9	5.9	6.9	V
VCE(sat)	Collector-Emitter Saturation Voltage	Ic=30A, VGE=15V, Tj=25°C	-	2.3	-	V
		Tj=125°C	-	2.8	-	
IcES	Collector-Emitter Leakage Current	VGE=0V, VcE=VCES, Tj=25°C	-	-	1.0	mA
IGES	Gate-Emitter Leakage Current	VGE=±20V, VcE=0V, Tj=25°C	-100	-	100	nA
Ciss	Input capacitance	VcE=25V, VGE=0V, f=1MHz	-	2485	-	pF
Coss	Output capacitance		-	157	-	
Crss	Reverse transfer capacitance		-	72	-	
Rgint	Internal gate resistor			1.3		Ω

Switching Characteristics

td(on)	Turn-on Delay Time	V _{cc} =600V, I _c =30A, V _{GE} =±15V, L=525uH, R _g =4.8Ω	T _j =25°C		21		ns
			T _j =125°C		21		
tr	Rise Time		T _j =25°C		24		ns
			T _j =125°C		25		
ta(off)	Turn-off Delay Time		T _j =25°C		93		ns
			T _j =125°C		100		
tr	Fall Time		T _j =25°C		286		ns
			T _j =125°C		360		
Eon	Turn-on Switching Loss		T _j =25°C		3.0		mJ
			T _j =125°C		3.3		
Eoff	Turn-off Switching Loss		T _j =25°C		1.5		mJ
			T _j =125°C		2.3		
ReJC	Junction-To-Case (IGBT)				0.36		K/W

Electrical Characteristics of Diode (T_J = 25°C unless otherwise noted)

Static characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
VFM	Forward Voltage	I _r =30A, V _{GE} =0V	T _J = 25°C		2.4	V
			T _J = 150°C		2.6	

Switching Characteristics

I	Peak Reverse Recovery Current	I=30A, V _{cc} =600V, V _{GE} =-15V, L=525uH, R _g =4.8Ω	T _j =25°C		54		A
			T _j =125°C		68		
Qr	Reverse Recovery Charge		T _j =25°C		4.5		μC
			T _j =125°C		7.3		
Erec	Reverse Recovery Energy		T _j =25°C		1.9		mJ
			T _j =125°C		3.3		
ReJC	Junction-To-Case(Diode)				0.95		K/W

Module Characteristics

T _j	Maximum Junction Temperature			150	°C
T _{JoP}	Maximum Operating Junction Temperature Range	-55		+150	°C
T _{stg}	Storage Temperature	-55		+150	°C

Characteristics diagrams

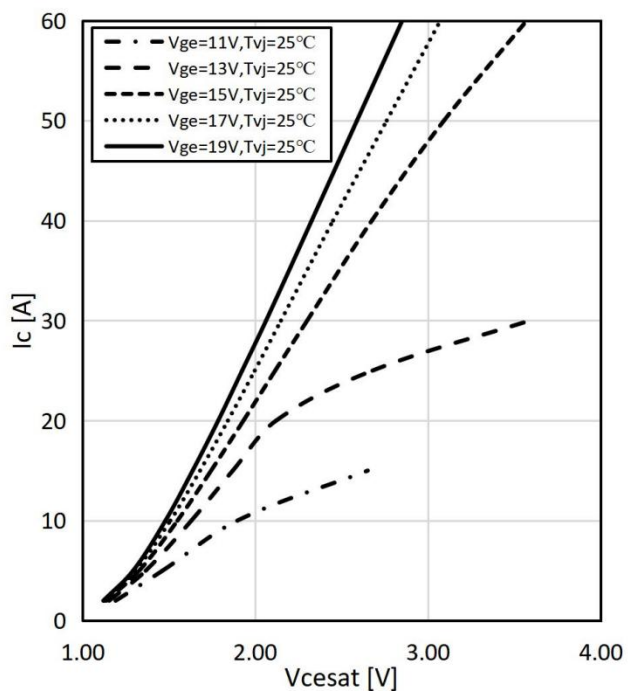


Fig.1 output characteristic IGBT Inverter(typical)

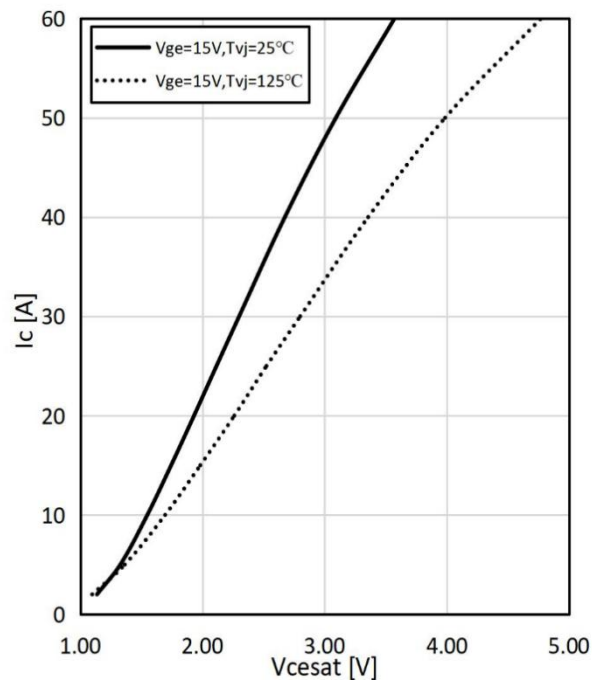


Fig.2 output characteristic IGBT Inverter(typical)

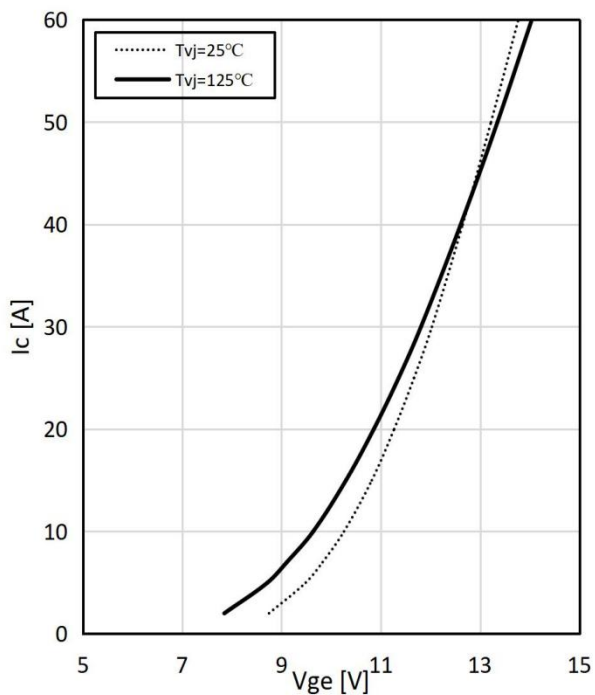


Fig.3 transfer characteristic IGBT Inverter(typical)

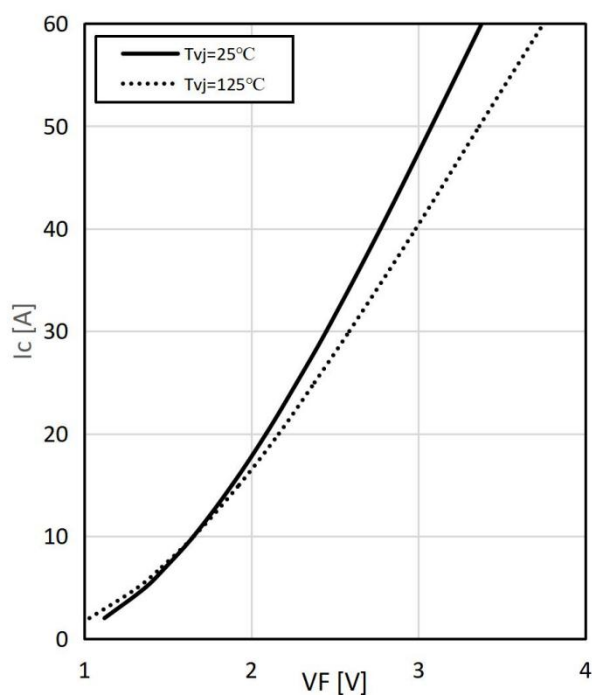


Fig.4 forward characteristic of Diode Inverter(typical)

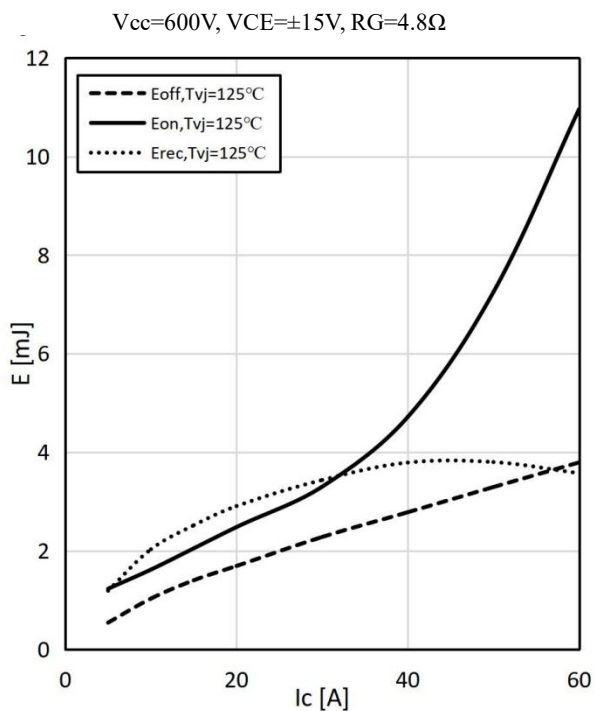


Fig.5 switching losses IGBT Inverter (typical)

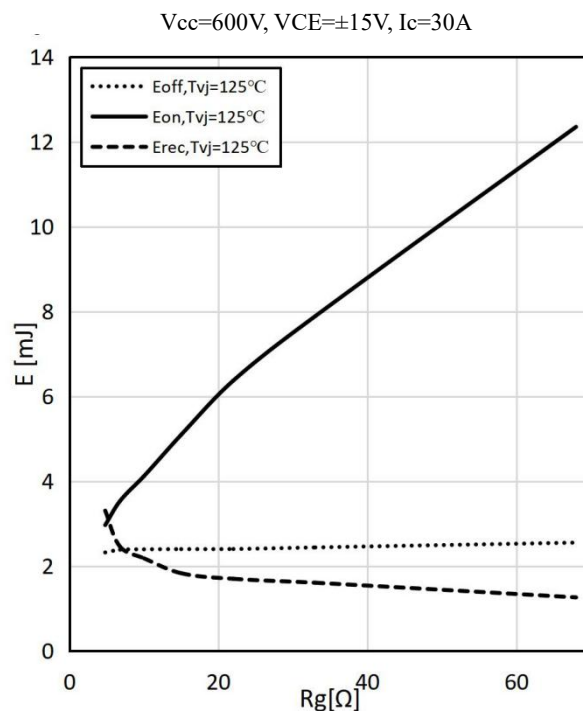


Fig.6 switching Losses vs. Gate Resistance (typical)

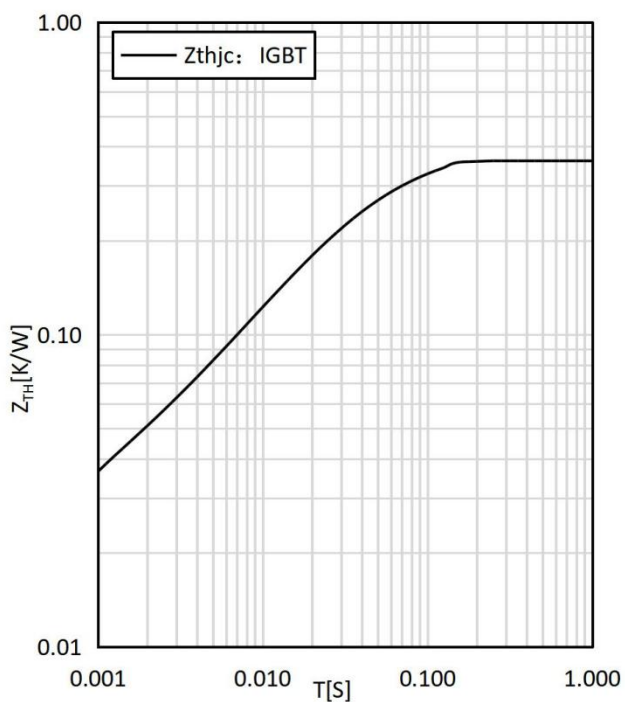


Fig.7 transient thermal impedance IGBT

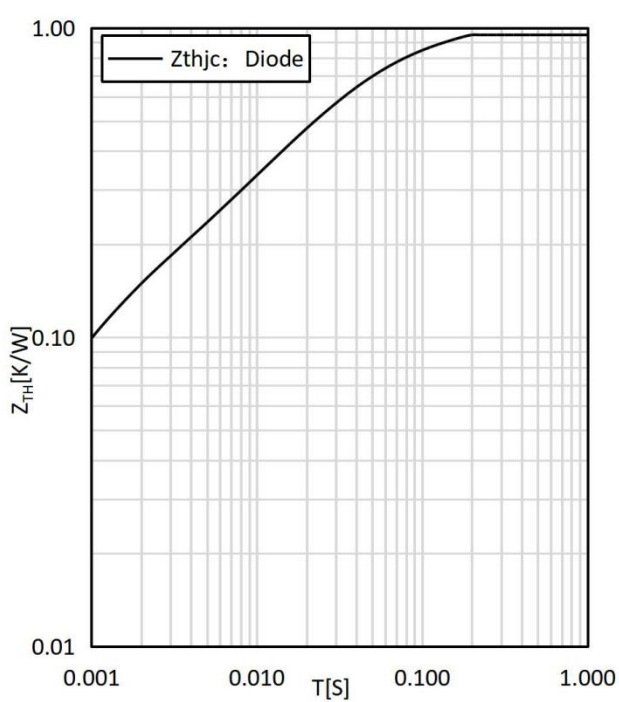
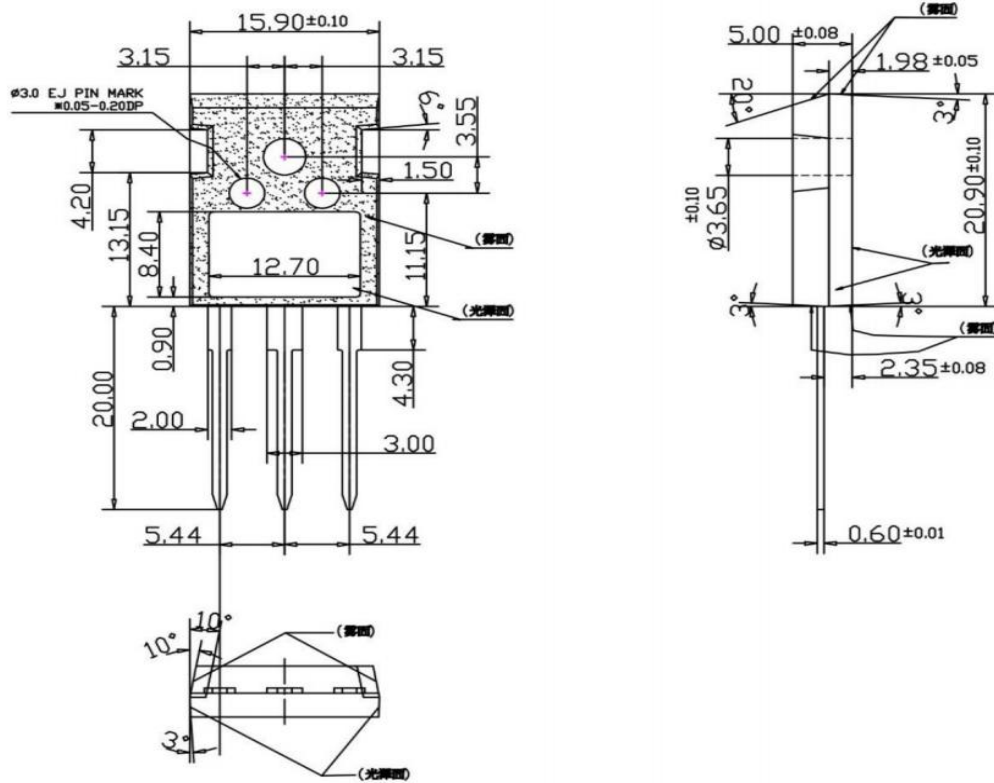


Fig.8 transient thermal impedance Diode

Package outline (mm)



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